

NCE 60V Complementary MOSFET

Description

The NCE603S uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

N channel

• V_{DS} =60V, I_D =5A $R_{DS(ON)}$ <60m Ω @ V_{GS} =10V

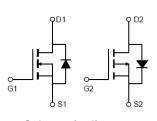
p channel

• V_{DS} =-60V, I_{D} =-4A $R_{DS(ON)}$ <80m Ω @ V_{GS} =-10V

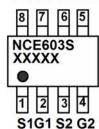
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

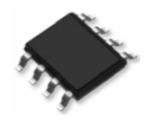
- H-bridge
- Inverters



Schematic diagram
D1 D1 D2 D2



Marking and pin assignment



SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE603S	NCE603S	SOP-8	Ø330mm	12mm	4000 units

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Paramete	Symbol	N-Channel	P-Channel	Unit		
Drain-Source Voltage		V _{DS}	60	-60	V	
Gate-Source Voltage	V _{GS}	±20	±20	V		
Continuous Dunin Cumant	T _C =25℃	1	5	-4	^	
Continuous Drain Current	T _C =100°C	l _D	3.5	-2.8	Α	
Pulsed Drain Current (Note 1)		I _{DM}	30	-30	Α	
Maximum Power Dissipation T _C =25℃		P _D	2	2	W	
Operating Junction and Storage Ten	T _J ,T _{STG}	-55 To 150	-55 To 150	$^{\circ}$ C		

Thermal Characteristic

N-channel	Thermal Resistance, Junction-to- Ambient (Note 2)	$R_{\theta JA}$	62.5	°C/W
P-channel	Thermal Resistance, Junction-to- Ambient (Note 2)	$R_{ heta JA}$	62.5	°C/W
N-channel	Thermal Resistance,Junction-to- Lead (Note 2)	$R_{ heta JL}$	30	°C/W
P-channel	Thermal Resistance, Junction-to- Lead (Note 2)	$R_{\theta JL}$	30	°C/W

N-Channel Electrical Characteristics (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	<u>.</u>					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	•		•			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.0	2.0	3.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =5A	-	37	44	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =5A	11	-	-	S
Dynamic Characteristics (Note4)			1	<u>I</u>		
Input Capacitance	C _{lss})/ 00)/// 0)/	-	450	-	PF
Output Capacitance	Coss	V_{DS} =30V, V_{GS} =0V,	-	61	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	27	-	PF
Switching Characteristics (Note 4)	.		J			
Turn-on Delay Time	t _{d(on)}		-	4.2	-	nS
Turn-on Rise Time	t _r	V_{DD} =30V , R_L =2.5 Ω	-	3.4	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{G} =3 Ω	-	16	-	nS
Turn-Off Fall Time	t _f		-	2	-	nS
Total Gate Charge	Qg	\/ 00\/1 5A	-	10		nC
Gate-Source Charge	Q _{gs}	V _{DS} =30V,I _D =5A,	-	2.4		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	3.6		nC
Drain-Source Diode Characteristics	•		•			
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =5A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	5	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =5A	-	27	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3) - 30 -		-	nC	
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD				

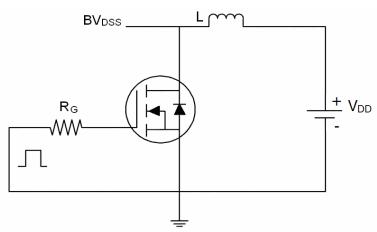
Notes:

- $\textbf{1.} \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature}.$
- 2. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with TA =25°C. The value in any a given application depends on the user's specific board design. The $R_{\theta JA}$ i is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient..
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production

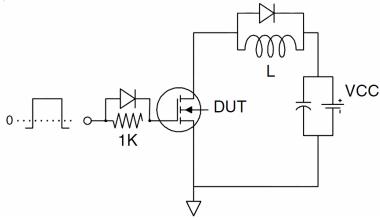


Test Circuit

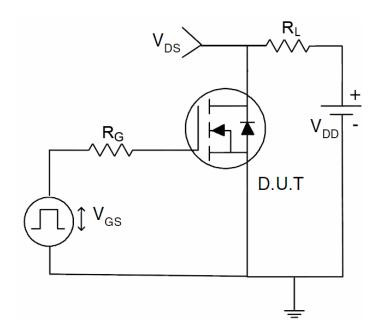
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





N-Channel Typical Electrical and Thermal Characteristics (Curves)

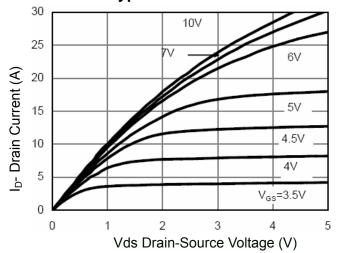


Figure 1 Output Characteristics

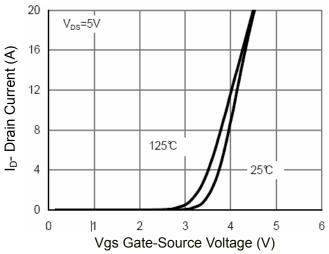


Figure 2 Transfer Characteristics

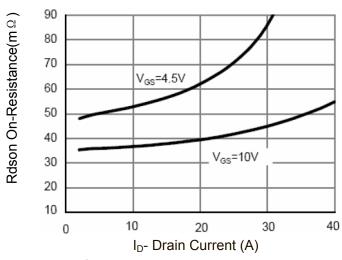


Figure 3 Rdson- Drain Current

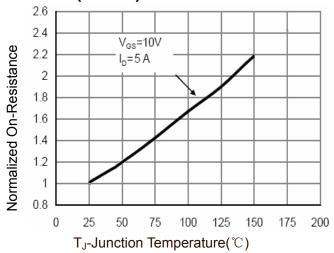


Figure 4 Rdson-Junction Temperature

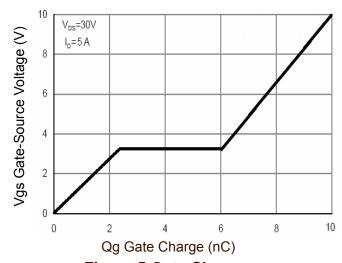


Figure 5 Gate Charge

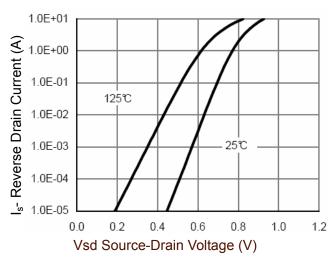


Figure 6 Source- Drain Diode Forward



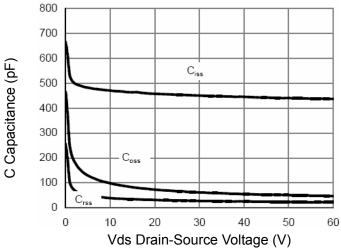
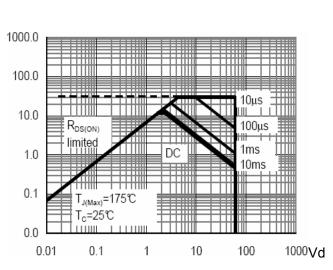


Figure 7 Capacitance vs Vds



s Drain-Source Voltage (V)
Figure 8 Safe Operation Area

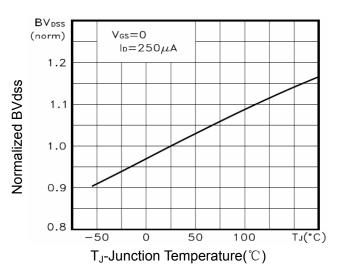


Figure 9 BV_{DSS} vs Junction Temperature

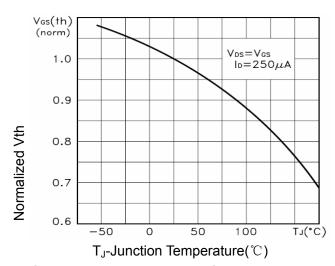


Figure 10 V_{GS(th)} vs Junction Temperature

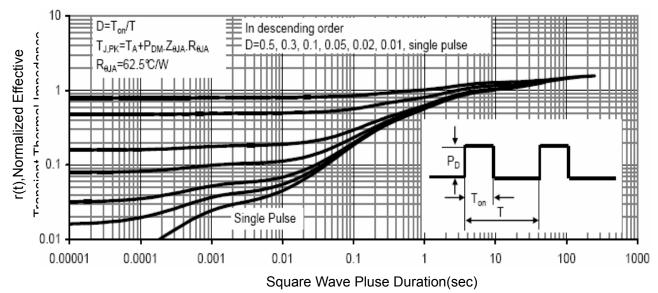


Figure 11 Normalized Maximum Transient Thermal Impedance



P-Channel Electrical Characteristics (T_C=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•	•		
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-60V,V _{GS} =0V	-	-	-1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	•		•	•		
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =-250μA	-1.5	-2.6	-3.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-4A	-	64	80	mΩ
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-4A	11	-	-	S
Dynamic Characteristics (Note4)			•	•		
Input Capacitance	C _{lss}	\/ 20\/\\ 0\/	-	960	-	PF
Output Capacitance	Coss	V _{DS} =-30V,V _{GS} =0V,	-	86	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	38	-	PF
Switching Characteristics (Note 4)	•		•	•		
Turn-on Delay Time	t _{d(on)}		-	9	-	nS
Turn-on Rise Time	t _r	V_{DD} =-30V , R_L =2.5 Ω	-	10	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =-10 V , R_G =3 Ω	-	25	-	nS
Turn-Off Fall Time	t _f		-	11	-	nS
Total Gate Charge	Qg	\/ 00\/ L 44	-	15.8		nC
Gate-Source Charge	Q_{gs}	$V_{DS}=-30V,I_{D}=-4A,$	-	3		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	3.5		nC
Drain-Source Diode Characteristics	•		•	•		
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =-4A	-		-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-4	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =-4A	-	27.5	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3) - 30 -		nC		
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				





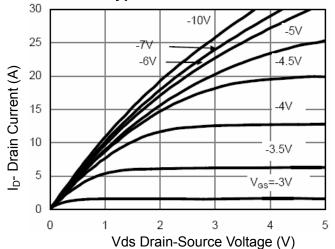


Figure 1 Output Characteristics

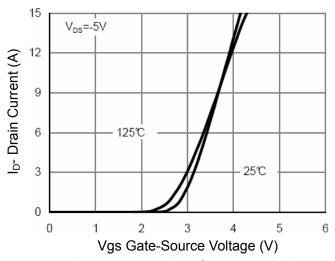


Figure 2 Transfer Characteristics

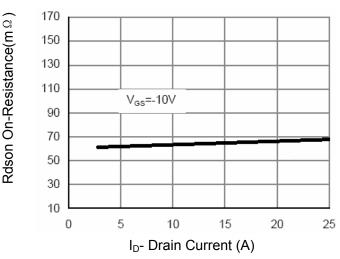


Figure 3 Rdson- Drain Current

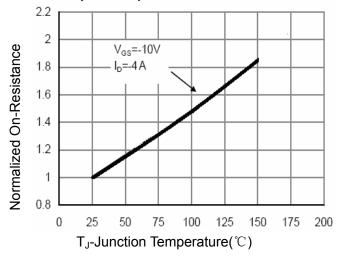


Figure 4 Rdson-Junction Temperature

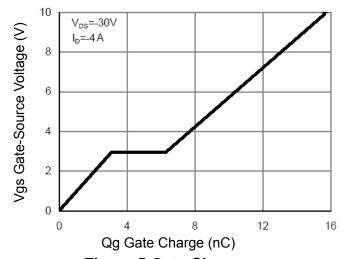


Figure 5 Gate Charge

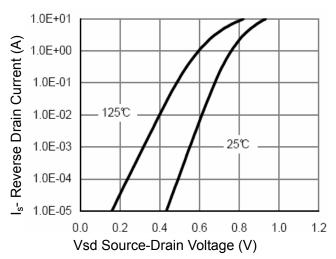


Figure 6 Source- Drain Diode Forward



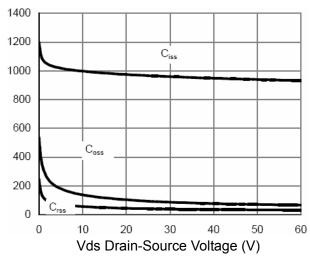


Figure 7 Capacitance vs Vds

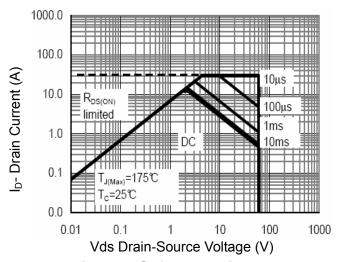


Figure 8 Safe Operation Area

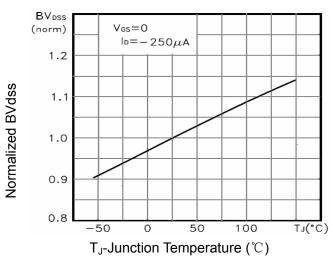


Figure 9 BV_{DSS} vs Junction Temperature

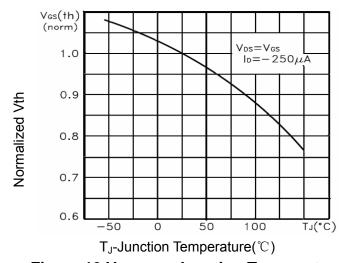


Figure 10 V_{GS(th)} vs Junction Temperature

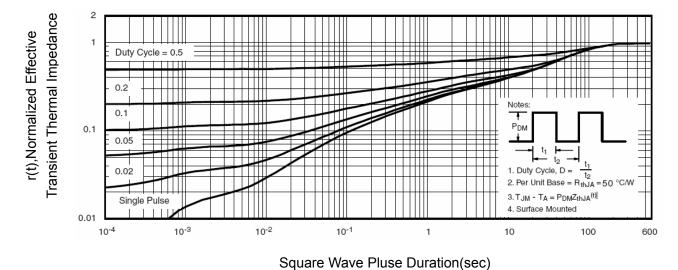
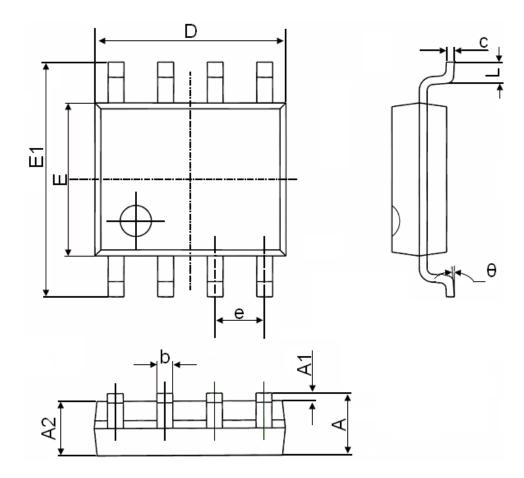


Figure 11 Normalized Maximum Transient Thermal Impedance



SOP-8 Package Information



Symbol	Dimensions I	n Millimeters	Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
А	1.350	1.750	0.053	0.069		
A1	0.100	0.250	0.004	0.010		
A2	1.350	1.550	0.053	0.061		
b	0.330	0.510	0.013	0.020		
С	0.170	0.250	0.006	0.010		
D	4.700	5.100	0.185	0.200		
Е	3.800	4.000	0.150	0.157		
E1	5.800	6.200	0.228	0.244		
е	1.270	1.270(BSC)		0.050(BSC)		
L	0.400	1.270	0.016	0.050		
θ	0°	8°	0°	8°		



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